# OPALE V2

Trusted and reliable embedded industrial PC's

# ■ Ready for OEM with Modified COST services

When generic doesn't fit, multi-Core OPALE V2 family, based on standard PICMG 1.3 form factor, offers flexibility to fit into many applications for OEM, System Integrators and Application Providers in a variety of domains: Test bench systems, FPGA/GPGPU intensive computing, rugged servers for harsh environments (Aero/Mil), high availability embedded computers for cybersecurity, vision, central data acquisition, control/command...

To precisely meet your requirements, even for small quantities, ECRIN Systems takes full system development responsibility and guarantee long term availability to allow you to concentrate on your added value and core business. From mechanical parts to industrial design, with front and remote user interfaces, user's LED's and I/O's, easy customized front and rear connectors fitting your activity, specific face-plate color and design, Lexan polycarbonate sheet with your logo and brand name, we will offer you a unique look that will shape your image and promote your sales.

- > Modified COTS with easy brand naming, configuration and customization for competition advantage
- > Security with Trusted boot
- > Local and remote active management to detect errors before they occur
- > Enhanced asset protection for continuous operation:
  - Durable connectors: 15 microinch Gold/Metal plated connectors assure long term reliability
  - Enhanced USB compatibility: USB power supply ensures stability (5V +/-5%)
  - Rugged EMI construction: EN55022 Class B radiation test, -10dB than competition Class A
- > MIL-STD tests passed (for T°C, shocks & vibrations, humidity, noise)
- > Reduced TCO with reporting Log file and downtime in harsh environments
- > Green power / Low noise at 37dBA (equivalent to no risk)
- > Long life management: up to 10 years by contract
- > Advanced Multi-Core "Skylake" boosted computing performance with DDR4 speeds and timings
- > Flexible backplane options for PCle configuration with dedicated bandwidth to accommodate GPGPU/FPGA intensive computing
- > Up to 14 full length cards / 451 mm depth only



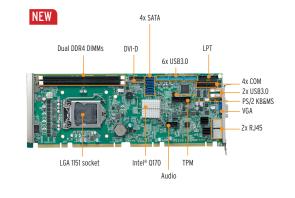
adquarters	Marketing & sales
, rue Louis Neel	2 - 12, rue du Chemin des Femr
c Technologique du Pré Roux	Immeuble l'Odyssée
920 Crolles - France	91300 Massy - France
	Tale 122 (0)1 (0 07 02 22

Rack specifications	
Construction	Anti-corrosion and long term heavy-duty steel, black color
Dimensions (W x H x D)	19''/4U with 17.8 inch depth (483x177x451mm)
Weight	18 kg (standard configuration)
Color	Black
Cooling	Three 92mm ball bearing low noise fans with monitoring
	Front access for easy maintenance
Power supply	PS2 form factor, compliant with Mini Redundant PSU
Drive bays	Two 5.25" front accessible drive bay
Backplane configuration	14 slots backplane, all for full length I/O boards
Front panel	Front door with lock, two USB and drive bay access
	Front door for dust filter and fan maintenance
	Embedded MMI, 4 LEDs with I/O capabilities
	Lexan for easy customization
Cards lock	Adjustable hold down bar for cards
	Rugged front holding parts for full length CPU and I/O cards
Packaging (W x H x D)	600 mm x 345 mm x 640 mm
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A: Dust filter & Fan access door B: LCD 2x16 characters C: Keyboard (Power & Reset) D: Lexan for easy customization E: 2 x USB (optional) F: 4 x tri-color LEDs G: Key lock H: Drive bay door

SHB specifications		
Form factor	PICMG 1.3 - Graphic Class / Server Class - PCI Express Gen 3	
Processor	LGA1151 socket - 6th Gen Intel® Core™ processor (codename Skylake)	
Chipset	Intel® Q170 Express chipset supporting PCI Express 3.0	
Memory	Dual-channel DDR4-2133 up to 32 GB (2* DIMM)	
Video	Integrated Intel® HD Graphics (VGA and DVI-D internal)	
BIOS	AMI® UEFI BIOS; 128 Mbit SPI Flash Memory	
Ethernet	2 x GbE (Intel® I219LM + Intel® I211-AT)	
	Intel® AMT and Wake On LAN support	
Disk	4x SATA 6Gb/s ports	
	Intel® Rapid Storage Technology, supports RAID 0/1/5/10	
Audio Codec	High Definition Audio interface with DB-Audio2 (option)	
USB	8x USB 3.0, 4x USB 2.0 (on backplane)	
Watchdog timer	24~65535 sec software programmable, can generate system reset	
Hardware monitoring	CPU & System temperature, fan speed and onboard DC voltages	
Manageability	SEMA support with BMC, SEMA Cloud	
SSI Trusted boot	1x box header for TPM module (optional) - Atmel AT97SC3204 TIS 1.2	
I/O peripherals	Serial port : 2x RS-232, 2x RS-232/422/485	
	Parallel port : 1x LPT port via onboard box header	
	KB/MS: 1x internal pin header for PS/2 keyboard/mouse	



Duckplane Specifications	
WBP-13E4	1xSHB / 1xPCle x8 / 3xPCle x4 / 8xPCl
EBP-13E4	1xSHB / 1xPCIe x16 / 3xPCIe x4 / 7xPCI
EBP-13E2	1xSHB / 1xPCle x16 / 1xPCle x4 / 10xPCl
EBP-10E5	1xSHB / 1xPCle x16 / 4xPCle x1 / 4xPCl
BPG7087	1xSHB / 4xPCIe x16 / 5xPCIe x4











Operating : 0~50°C / Storage -20~80°C (MIL-STD-810F, method. 502.4 proc II)			
Operating : 5 à 95% non condensing			
0-3000m (0-10.000ft) operating			
Operating: 15G, 11ms 6 axis (MIL STD 810 F, method. 516.5) - 5~100 Hz 0.8G (MIL STD 810 F, method. 514.5)			
37 dBA (MIL-STD-740-1)			
EMC: 2014/30/UE; EN 61000-6-2, EN55022, EN 55024 - SAFETY: 2014/35/UE; EN60950-1: 2006 2 <sup>™</sup> edition A11: 2009 + A1: 2010 + A12: 2011 + A2: 2014			

- > Intel® AMT for remote management
- > Local control with embedded MMI (Windows & Linux services)
  - FAN control & monitoring
  - System & network information - Watchdog & elapsed time counter
  - Redundant P/S default
- Alarm (fan, temperature, redondant P/S), Log file
- User script launch form menu entry
- Easy configuration with .TXT file

- > Branding user's Lexan Costless, NRE fees only
- > Modified COTS customization:
- Front panel design
- Specific I/O on front panel / special connectors on rear panel
- Specific H/W configurations
- Specific S/W functionality

Call us for more information .

Standard configuration				
	Power Supply Unit ATX 12V - 400W - High Efficiency 80+		Processor	- Intel® Core™ i7-6700 (4C/8T, 3.4 GHz, 8M Cache, 14nm, 65W TDP)
		90 ~ 240 VAC full range / 47~63 Hz		- Intel® Core™ i7-6700TE (4C/8T, 2.4 GHz 8M Cache, 14nm, 35W TDP)
		5V@20A, 12V@30A, -12V@0.8A, 3.3V@20A, 5Vstb@3.5A		- Intel® Core™ i5-6500 (4C/4T, 3.2 GHz, 6M Cache, 14nm, 65W TDP)
		Option for 2x 500W Redundant P/S		- Intel® Core™ i5-6500TE (4C/4T, 2.3 GHz, 6M Cache, 14nm, 35W TDP)
		90-240VAC full range / 47-63Hz		- Intel® Core™ i3-6100 (2C/4T, 3.7 GHz, 3M Cache, 14nm, 51W TDP)
	Backplane	WBP-13E4		- Intel® Core™ i3-6100TE (2C/4T, 2.7 GHz, 4M Cache, 14nm, 35W TDP)
	Drives	1 x Slim DVDRW	Memory	DDR4-2133 : 4Go / 8Go / 16Go / 32Go
		1 x 2.5" SATA Removable Drive	Disk	- 2.5" 7200 RPM Hard Drive (500Go ~ 1To)
		1 x 5.25" front accessible drive bay free		- SLC and/or MLC Solid State Drive (32 Go ~ 2To)
		(up to 4x removable 2.5" HD or SSD)		- Up to 4x hot swap 2.5" HD/SSD with optional 4in1 drive bay
	Front I/O (behind door)	2x USB 2.0	OS	- Microsoft® Windows® 7 32/64-bit, Windows 8.1 & 10 64-bit
	Rear I/O	VGA + 2xGbE + 4xUSB 3.0 + 2xCOM		- Linux 32/64-bit

# sales@ecrin.com

### Hea

143, Parc 389 Tel: +33 (0)4 76 92 20 01

## www.ecrin.com

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